

QUALITEK[®] 813 WATER SOLUBLE HALOGEN-FREE FLUX

Description

Qualitek[®] 813 is a Halogen-Free Water Soluble Flux designed for wave soldering and surface mount assembly applications. 813 flux is best for foaming applications by providing a stable head of light bubbles. 813 may also be used for lead tinning applications.

Main Features

- □ Halogen-Free
- Excellent for lead tinning
- □ Remains active at high temperatures
- Compatible with leaded and lead-free systems

Technical Data

	Specification	Test Method
Flux Classification	ORL0	IPC-J-STD-004B
Color and Appearance	Light Amber Liquid	
Copper Mirror	No removal of copper film	IPC-TM-650 2.3.32
Specific Gravity (g/cm ³)	0.870 ± 0.006	
pH (5% aqueous soln)	3.0 ± 0.5	
Solids Content, % Wt.	13.5 ± 0.5	IPC-TM-650 2.3.34

Applications

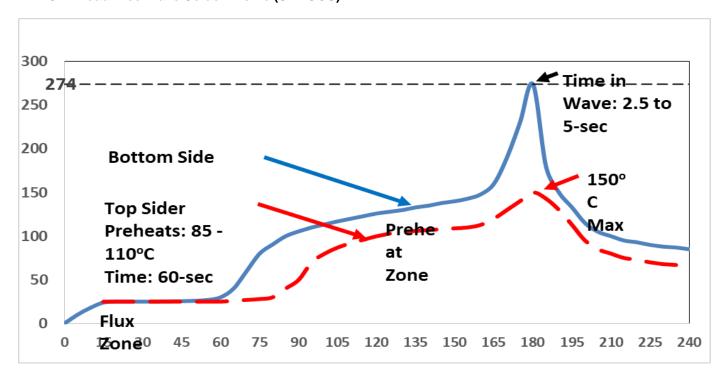
Flux Application

For mass wave soldering of OSP and plated circuit boards, spray, foam or wave fluxing can be utilized to apply this flux. If foam fluxing, the foam fluxer should be supplied with compressed air, which is free of oil and water. The flux tank should be full at all times. The surface of the flux should be 1-½ inches above the top of the flux aerator, or flux stone. Pressure should then be adjusted to produce the optimum foam height with a fine uniform foam head. After fluxing, an air knife should be used to remove excessive flux from the assembly.

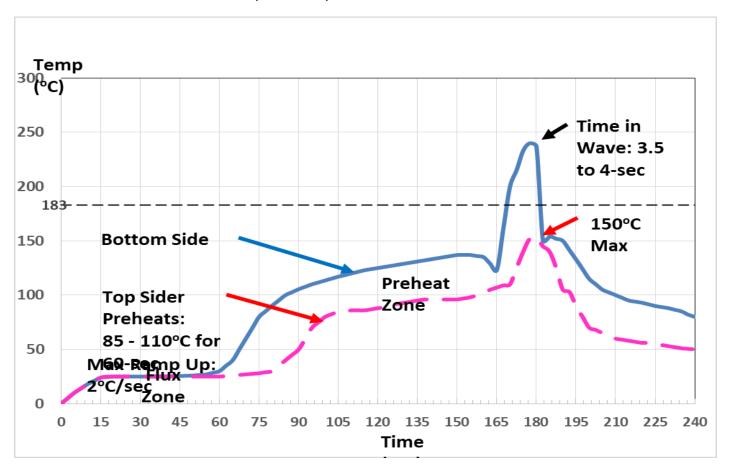
Uniformity of the spray flux coating can be visually checked by running a tempered glass plate (usually supplied by machine manufacturer) through the spray and preheat sections, and inspected before going across the wave.

OPERATING PARAMETERS	TYPICAL LEVEL
Amount of flux	Foam, Wave: 1000-2000 μg/in ² solids
	Foam, Wave: 1000-2000 µg/in² solids Spray: 750-1500 µg/in² solids
Foam Fluxing Parameters	
Foam Stone Pore Size	20-50 μm
Flux Level Above Stone	1-1 ½ inches (25-40mm)
Chimney Opening	3/8-1/2 inch (10-13 mm)
Air Pressure	1-2 psi
Top Side Preheat Temperature	190-230 °F (85-110 °C)
Bottom Side Preheat Temperature	65 °F (35 °C) higher than topside
Conveyor Speed	4-6 feet/minute(1.2-1.8 meters/minute)
Contact Time in the Solder (including Chip & Lambda)	2.5-4.5 seconds
Solder Pot Temperature	
	491-500 °F (255-260 °C)
SnAgCu	520-530 °F (271-276 °C)

TYPICAL Lead Free Wave Solder Profile (SNAGCU)



TYPICAL Leaded Wave Solder Profile (Sn63/Pb37)



Process Control

Control of flux during use is necessary to assure a consistent amount of flux is applied to assemblies. Monitoring and controlling specific gravity is recommended for maintaining the proper flux concentration. Density (specific gravity) can performed using a hydrometer. Control of the flux can be achieved with 800T thinner to maintain fluxing activity. We recommend replacing the flux periodically for consistent performance and to minimize build-up.

Flux Residues and Cleaning

As with all water-soluble fluxes, post-soldering cleaning is required. Residues can be easily removed with both hot and cold water; therefore, no neutralizer is needed. We recommend de-ionized water be used in the final rinse. Spray pressures should be maintained at 20-30 psi and conveyor speed of 3-6 ft. /min.

Storage & Shelf Life

Liquid flux should be stored in dry, well-ventilated area, away from direct heat and flame. Shelf life is 2 years from date of manufacture.

Packaging

813 Liquid Flux is available in 1 Gallon and 5 Gallon containers and 55 Gallon drums.

<u>Disposal</u>

813 contains hazardous ingredients, therefore, should be disposed of in accordance with federal, state, and local authority requirements.

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